



SABIC® LDPE HP0723JN

LOW DENSITY POLYETHYLENE

DESCRIPTION

HP0723JN is a fractional melt index low density polyethylene resin, containing slip and antiblock additives. HP0723JN has been specially designed for superior processability on blown films lines leading to significant output improvements. The resin offers additionally excellent draw down. It can be used pure or in blends with LLDPE resins. HP0723JN Contains Slip and antiblock additives. LDPE HP073JN has low gel levels.

- Excellent processability and draw down
- Good physical properties in blends with LLDPE
- Can be readily extruded using conventional blown films techniques at melt temperatures between 160 and 195°C

TYPICAL APPLICATIONS

- Lamination films, Collation shrink, Shopping bags, Garbage bags.
- Health & hygiene films, Food packaging, Collation shrink, Agricultural films.

TYPICAL PROPERTY VALUES

| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|---|----------------|-------------------|--------------|
| POLYMER PROPERTIES ⁽¹⁾ | | | |
| Melt Flow Rate (MFR) | | | |
| at 190°C and 2.16kg | 0.75 | g/10 min | ASTM D1238 |
| Density | | | |
| at 23°C | 0.923 | g/cm ³ | ASTM D792 |
| MECHANICAL PROPERTIES ^{(1) (2)} | | | |
| Dart Impact Strength | 6 | g/μm | ASTM D1709 |
| OPTICAL PROPERTIES | | | |
| Gloss (45°) | 58 | % | ASTM D2457 |
| Haze | 9 | % | ASTM D1003 |
| FILM PROPERTIES ^{(1) (2)} | | | |
| Tensile Properties | | | |
| 1% secant modulus, MD | 175 | MPa | ASTM D882 |
| 1% secant modulus, TD | 185 | MPa | ASTM D882 |
| stress at yield, MD | 11.0 | MPa | ASTM D882 |
| stress at yield, TD | 11.0 | MPa | ASTM D882 |
| stress at break, MD | 25.0 | MPa | ASTM D882 |
| stress at break, TD | 23.0 | MPa | ASTM D882 |
| strain at break, MD | 390 | % | ASTM D882 |
| strain at break, TD | 570 | % | ASTM D882 |
| Elmendorf Tear Strength ⁽²⁾ | | | |
| MD | 10 | g/μm | ASTM D1922 |
| TD | 6 | g/μm | ASTM D1922 |

(1) Properties have been measured by producing 50 μ film with 2.5 BUR using 100%

(2) Typical values: not to be construed as specification limits.